g GE Energy	**Functional Testing Specification**
Parts & Repair Services ***Louisville, KY***	**LOU-GED-IS230TBAIxxxxx**

Test Procedure for an IS230TBAIxxxxx Mark VIe Terminal Board Assembly.

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	J. Francis	12/07/2015

PREPARED BY	REVIEWED BY	REVIEWED BY	QUALITY APPROVAL
J. Francis			L. Groves
DATE	**DATE**	**DATE**	**DATE**
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1. SCOPE

1.1 This is a functional testing procedure for an **IS230TBAIxxxxx** MARK VIe Terminal board assembly.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
3.1.1 Check board's electronic folder for more information.

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning
4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
4.2 Equipment Inspection
4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
4.2.1.1 Wires - broken, cracked, or loosely connected
4.2.1.2 Terminal strips / connectors - broken or cracked
4.2.1.3 Components - visually damaged
4.2.1.4 Capacitors - bloated or leaking
4.2.1.5 Solder joints - damaged or cold
4.2.1.6 Circuit board - burned or de-laminated
4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
3		Fluke 87 DMM (or Equivalent)

6. TESTING PROCESS

6.1 Testing Procedure

Note: This procedure will be for an entire *IS230TBAIxxxxx* assembly. Since we do NOT have a fully functional assembly test, the assembly will be broken down to individually test each sub-assembly separately using its assigned test. The test procedure will be listed for each sub-

assembly.

6.1.1 Remove the **IS200TBAI** card and test using test procedure ***LOU-GED-TMR-RST-A***, referring to Models Database for latest revision of test procedure.

6.1.2 Remove the **IS220PAIC PAC Modules** and test using test procedure ***LOU-TOFFEE-IS220PAIC-B***, referring to Models Database for latest revision of test procedure.

6.1.3 Remove the **IS200JPDL** card and test using test procedure ***LOU-GED-IS200JPDL-A***, referring to Models Database for latest revision of test procedure.

6.1.4 Remove the **IS200JGND** cards and test using test procedure ***LOU-GED-IS200JGND-A***, referring to Models Database for latest revision of test procedure.

6.2 ***TEST COMPLETE ***

7. NOTES

7.1 None at this time.

8. ATTACHMENTS

8.1 None at this time.